

United States Patent [19]

Doornveld

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[54] **METHOD AND APPARATUS FOR APPLYING A LAYER OF PHOTOSENSITIVE MATERIAL TO A SEMICONDUCTOR WAFER**

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B29C 37/00; B05C 11/12

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156/345; 156/655; 156/668; 427/240

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152/668, 639; 427/240; 118/52

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[57] ABSTRACT

In a method of applying a layer of photosensitive material to a semiconductor material wafer (3), the photosensitive material is applied in liquid form to the wafer and the wafer is then rotated in order to obtain the desired thickness of the layer. Photosensitive material (7) present at the edge (6) of the wafer (3) is removed by means of a jet of a liquid directed onto this edge to dissolve the photosensitive material, the jet being directed first to an area beyond the wafer of semiconductor material, where upon the jet of liquid is directed to the edge of the wafer and finally the jet of liquid is directed again to an area beyond the wafer and the supply of liquid is switched off.

3 Claims, 3 Drawing Figures

